THERMOCOMP™ COMPOUNDS FOR LASER DIRECT STRUCTURING SOLUTIONS

Laser Direct Structuring is used to produce 3D parts such as printed circuit board and antenna via activated 3D surface for proper metallization. LNP™ THERMOCOMP™ LDS (Laser Direct Structuring) compounds can help increase productivity of 3D-MID’s (molded interconnected devices). Such thermoplastic parts with integrated electronic circuit can provide design cycle flexibility, through part consolidation and miniaturization versus conventional technologies, such as metal stamping. This can potentially provide system cost-out due to a shorter value chain and faster market introduction.

TYPICAL LASER DIRECT STRUCTURING PROCESS:

- **THERMOCOMP™ LDS compounds**
- **Part Molding**
- **Laser Activation**
- **Metallization**

POTENTIAL BENEFITS OF LASER DIRECT STRUCTURING:

- Full 3D capability - system integration
- Fast and easy design changes – increased speed to market
- No layout specific tooling - lower cost
- Fine pitch resolution - miniaturization
- High cost efficiency - fine structure and small production
LNP™ COMPOUNDS & LEXAN™ COPOLYMER RESINS

Over 70 years of innovation in thermoplastic compounding enables SABIC’s specialty compounds to offer extensive materials with a broad portfolio.